

PATENT ASSIGNMENT COVER SHEET

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Assignment ID: PAT1451308

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	LIEN
CONVEYING PARTY DATA	
Name	Execution Date
Ovik LEONARDOVICH MKRTCHYAN	05/01/2024
RECEIVING PARTY DATA	
Individual Name:	Raymond Van Dyke
Street Address:	1050 Connecticut Avenue NW POB 65302
City:	Washington
State/Country:	DISTRICT OF COLUMBIA
Postal Code:	20035
PROPERTY NUMBERS Total: 11	
Property Type	Number
Application Number:	17990848
Application Number:	16686423
Application Number:	17843682
Patent Number:	9879329
Patent Number:	10570466
Patent Number:	11505837
Patent Number:	9957579
Patent Number:	9873922
Patent Number:	10478514
Patent Number:	11364889
Patent Number:	10920289
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2023783903
Email:	ray@vandykeiplaw.com
Correspondent Name:	Raymond Van Dyke
Address Line 1:	1050 Connecticut Avenue NW POB 65302
Address Line 4:	Washington, DISTRICT OF COLUMBIA 20035

ATTORNEY DOCKET NUMBER:	IntellSphere-1
NAME OF SUBMITTER:	Raymond Van Dyke
SIGNATURE:	Raymond Van Dyke
DATE SIGNED:	08/24/2024
Total Attachments: 3 source=Lien-Notarized#page1.tiff source=Lien-Notarized#page2.tiff source=Lien-Notarized#page3.tiff	

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**AFFIDAVIT FOR PATENT LIEN ON U.S. PATENTS AND PATENT APPLICATIONS
AND ALL PATENTS ISSUING THEREFROM**

WHEREAS, I, Raymond Van Dyke of Van Dyke Intellectual Property Law (hereinafter designated as the undersigned) am the counsel for Applicant and/or Inventor Ovik Leonardovich Mkrtchyan (hereinafter designated as client) through foreign counsel IntellSphere;

WHEREAS the undersigned, at the behest of the client, prepared and filed a number of provisional, utility and PCT patent applications, and advised the company on all matters IP, all listed hereinbelow;

WHEREAS the client has numerous invoices unpaid for the patents and patent and trademark applications listed hereinbelow, with a total in excess of \$27,000 owed as of the date of this document.

NOW THEREFORE, to all whom it may concern, be it known that the undersigned asserts sufficient financial interest in the subject matters of the below-identified patents and patent applications, to obtain full payment of any and all amounts due and owing, establishes this lien over each and every case, which extends to all inventions and improvements disclosed in the aforesaid patents and patent applications, and in and to the patents and patent applications, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the inventions and improvements, including any assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom;

AND furthermore, the undersigned intends to take all necessary actions to make their financial interests in these patents, patent applications official in the records of the U.S. Patent & Trademark Office, and files this document as a lien and encumbrance against any other persons, companies and interests, commercial or non-profit, particularly any companies or individuals in commerce with the client, which shall be effective until such time as the outstanding debt is paid in full, at which point the undersigned shall file the requisite documentation to reflect said full payment and negate this lien.

AND the listing of such patents, patent applications and trademark applications, as of today's date, are set forth as follows:

Issued Patents:

U.S. Patent Nos. 9,873,922;
 9,879,329;
 9,957,579;
 10,478,514;
 10,570,466;
 10,920,289;
 11,364,889; and
 11,505,837;

Pending Patent Applications:

U.S Patent Application Serial Nos. 16/686,423;
 17/843,682; and
 17/990,848 and any other related cases;

